

# Development of large-area topological insulators on Silicon for spintronics

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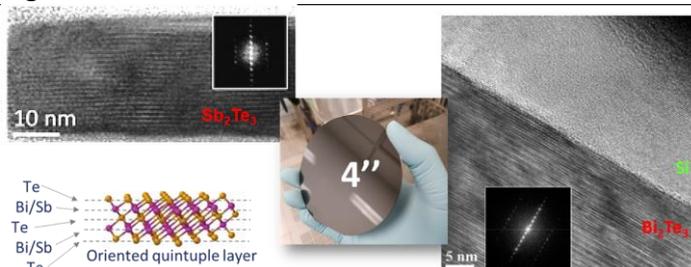
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Topological insulators (TIs) are gaining a huge attention from a technological point of view due to highly efficient spin-charge interconversion phenomena occurring at their interface with magnetic materials, which is of interest for spin-orbit torque MRAM [1] and novel processing-in-memory devices such as the MESO proposed by Intel [2]. We developed Metal Organic Chemical Vapour Deposition (MOCVD) processes to grow epitaxial-quality  $\text{Sb}_2\text{Te}_3$  and  $\text{Bi}_2\text{Te}_3$  3D-TIs on 4" Si(111) substrates [3-5], see Figure. 1. First, their topological character has been demonstrated by combining magnetotransport and angular photoemission spectroscopy studies [6]. Then, we built simple spin-charge converters by interfacing the TIs with ferromagnetic layers (FM=Fe,Co). Within this talk, we report a large spin-charge conversion efficiency in the FM/ $\text{Sb}_2\text{Te}_3$ -based systems, as expressed in terms of the generated inverse Edelstein Effect ( $\lambda_{IEE}$ ) extracted from spin pumping ferromagnetic resonance (SP-FMR) [7,8]. Values of  $\lambda_{IEE}$  up to 0.61 nm were measured [8], indicating quite a large conversion efficiency within the class of second generation 3D chalcogenide-based TIs (Figure 2). Our results open interesting routes toward the use of chemical methods to produce TIs over large area Si substrates and characterized by highly performing spin-to-charge conversion, thus marking a milestone toward future technology-transfer.

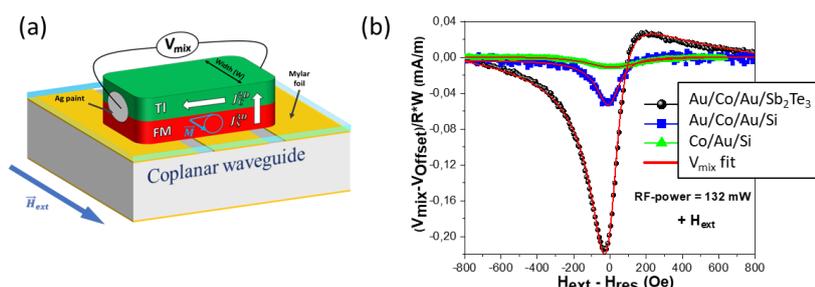
## References

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## Figures



**Figure 1:** Transmission electron microscopy images of MOCVD-grown TIs on 4" Si(111).



**Figure 2:** SP-FMR (a) sample's configuration and (b) results obtained in Au/Co/Au/ $\text{Sb}_2\text{Te}_3$ /Si(111) spin-charge converter.